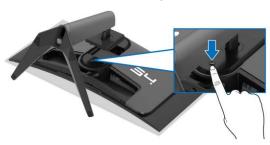
1. Disassembly Procedures

- S1 Turn off the monitor.
- S2 Place the monitor on AW3423DW Curve Sponge Jig

Press and hold the stand release button at the back of the display



S3 Lift the stand assembly up and away from the monitor



S4 Unlock 4 screws on Rear Cover

Use hands and scraper bar to gently disassemble Rear Cover from the monitor.

Notice the disassembly order: Left Side/ Right Side=> Top side=>Bottom Side



(Screw Torque: 8~9 kgf)

S5 Gently pull up Rear Cover from bottom side to top side



S6 Disconnect "WIRE 6P/4P/4P" and "CTRL BD to I/F BD FFC" from I/F BD

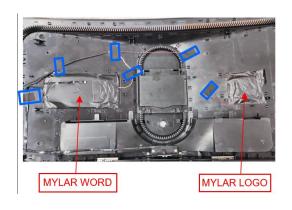
Take off Rear Cover from monitor head



Tear off 6 acetate tapes from "WIRE 6P/4P/4P" and Rear Cover

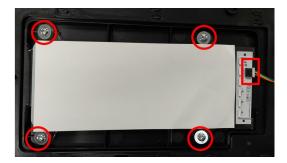
Tear off "MYLAR WORD" from Rear Cover

Tear off "MYLAR LOGO" from Rear Cover



S8 Unlock 4 screws to disassemble "ASSY LED MOUDLE" from Rear Cover

Unplug "WIRE 6P/4P/4P" from "ASSY LED MOUDLE"



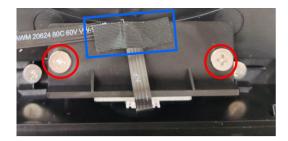
(Screw Torque: 4.5±0.5 kgf)

S9 Unplug "WIRE 6P/4P/4P" from LED BD
Disassemble LED BD from Rear Cover



S10 Tear off a tape from "CTRL BD to I/F BD FFC" on "FRAME JS"

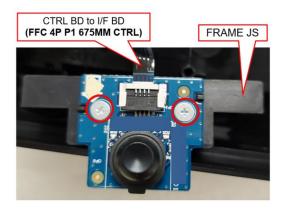
Unlock 2 screws to disassemble "FRAME JS" from Rear Cover



(Screw Torque: 3.0-4.0 kgf)

S11 Unlock 2 screws to disassemble "CTRL BD" from "FRAME JS"

Unplug "CTRL BD to I/F BD FFC" from CTRL BD

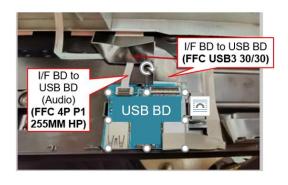


(Screw Torque: 1.6-1.7 kgf)

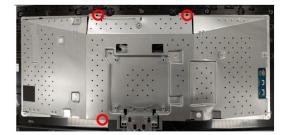
\$12 Unplug "LENS BD FFC" from I/F BD



- \$13 Unplug following cables from USB BD
 - 1) FFC USB3 30/30
 - 2) FFC 4P P1 255MM HP



S14 Unlock 3 screws to disassemble Main SHD from panel



(Screw Torque: 4~4.5 kgf)

S15 Unplug "I/F BD to Thermal Sensor BD FFC cable" from "Thermal Sensor BD"

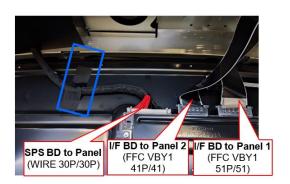


S16 Unplug following cables from panel

- 1) FFC VBY1 51P/51
- 2) FFC VBY1 41P/41
- 3) WIRE 30P/30P

Tear off a long tape from "WIRE 30P/30P" on panel

Take off Main SHD from Panel



S17 Tear off a fabric conductive tape from panel and USB BD

Unlock 1 screw to disassemble USB BD from Middle Frame



(Screw Torque: 3.5-4.0 kgf)

S18 Unlock 7 ASSY CHIN screws (See blue mark)

Unlock 17 Middle Frame screws (See red mark)

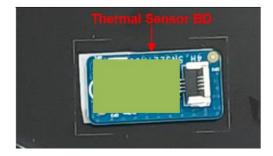


(Screw Torque-CHIN: 1.6-1.7 kgf) (Screw Torque-MF: 4-4.5 kgf)

S19 Disassemble "Middle Frame and "ASSY CHIN" from panel



S20 Tear off "Thermal Sensor BD" from panel



S21 Tear off panel mylar panel (See yellow mark)

Tear off 1 top fabric conductive tape from panel (See blue mark)

Tear off 2 bottom fabric conductive tapes from panel (See pink mark)

Tear off left and right fabric conductive tapes from panel (See red mark)



S22 Tear off a sponge from Middle Frame



S23 Unlock 2 screws to disassemble "LENS BD " from Middle Frame



(Screw Torque: 1.2-1.3 kgf)

S24 Disassemble "BTN PWR" from Middle Frame



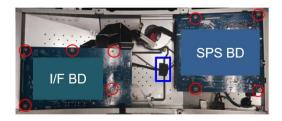


S25 Disassemble Mylar from Main SHD



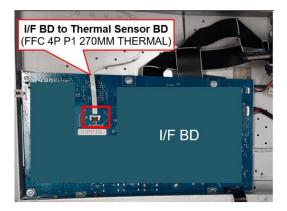
S26 Unlock 9 PCBA screws

Tear off a tape from Main SHD

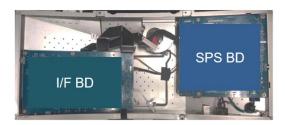


(Screw Torque: 8-9 kgf)

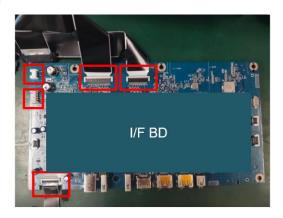
S27 Unplug "I/F BD to Thermal Sensor BD FFC" from I/F BD



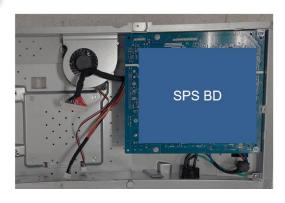
\$28 Disassemble I/F BD from Main SHD



S29 Unplug all cables from I/F BD



\$30 Disassemble SPS BD from Main SHD



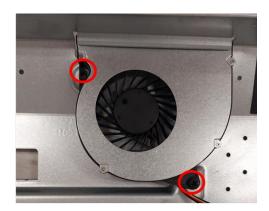
S31 Unplug "WIRE AC+3P" from SPS BD



\$32 Unplug all cables from SPS BD

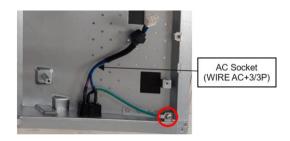


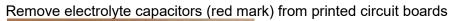
S33 Unlock 2 screws to disassemble Fan from Main SHD

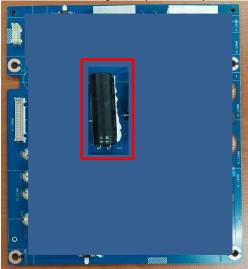


(Screw Torque: 8.5±1 kgf)

Unlock 1 ground screw to disassemble "WIRE AC+3P" from Main SHD

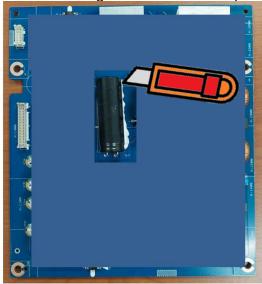




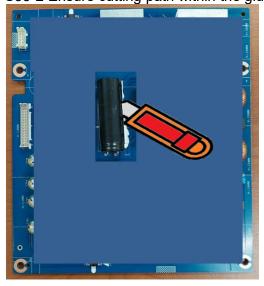


S35

S35-1 Cut the glue between bulk cap. and PCB with a knife



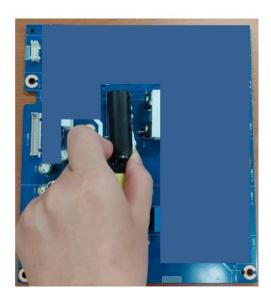
S35-2 Ensure cutting path within the glue, don't touch bulk cap. or PCB



S35-3 Take out bulk cap. pin solder with soldering iron and absorber



S35-4 Lift the bulk cap. up and away from the PCB



2. Product material information

The following substances, preparations, or components should be disposed of or recovered separately from other WEEE in compliance with Article 4 of EU Council Directive 75/442/EEC.

Capacitors / condensers (containing PCB/PCT)	No used
Mercury containing components	No used
Batteries	No used
Printed circuit boards (with a surface greater	Product has printed circuit boards
than 10 square cm)	(with a surface greater than 10 square
	cm)
Component contain toner, ink and liquids	No used
Plastic containing BFR	No used
Component and waste contain asbestos	No used
CRT	No used
Component contain CFC, HCFC, HFC and	No used
HC	
Gas discharge lamps	No used
LCD display > 100 cm2	Product has an LCD greater than 100
	cm2
External electric cable	Product has external cables
Component contain refractory ceramic fibers	No used
Component contain radio-active substances	No used
Electrolyte capacitors (height	Product has electrolyte capacitors
> 25mm, diameter > 25mm)	(height >25mm, diameter > 25mm)

3. Tools Required

List the type and size of the tools that would typically can be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description:

- Screwdriver
- Scraper Bar
- Penknife
- Soldering iron and absorber
- AW3423DWB Curve Sponge Jig